

# 10A, 200V - 600V Super Fast Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Very low profile, typical height of 1.1mm
- 175°C operating junction temperature
- Glass passivated chip junction
- Low conduction loss
- Low leakage current
- High forward surge capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

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- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

#### **MECHANICAL DATA**

- Case: TO-277A (SMPC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.095g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F</sub>	10	Α		
$V_{RRM}$	200 - 600	V		
I <sub>FSM</sub>	150	Α		
$T_{JMAX}$	175	°C		
Package	TO-277A (SMPC)			
Configuration	Single die			

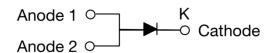








**TO-277A (SMPC)** 



PARAMETER	SYMBOL	TPMR10DH	TPMR10GH	TPMR10JH	UNIT
Marking code on the device		MR10D	MR10G	MR10J	
Repetitive peak reverse voltage	$V_{RRM}$	200	400	600	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	140	280	420	V
Forward current	I <sub>F</sub>	10		Α	
Surge peak forward current 8.3ms single half sine wave superimposed on rated load	I <sub>FSM</sub>	150		А	
Junction temperature	TJ	-55 to +175		°C	
Storage temperature	T <sub>STG</sub>	-55 to +175			°C

1

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance <sup>(1)</sup>	$R_{\Theta JL}$	8.4	°C/W		
Junction-to-ambient thermal resistance (2)	R <sub>OJA</sub>	78	°C/W		

## Notes:

- 1. Mounted on FR4 PCB with 16mm x 16mm Cu pad area
- 2. Free air, mounted on recommended pad

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT	
	TPMR10DH		V <sub>F</sub>	-	0.95	V
	TPMR10GH	$I_F = 10A, T_J = 25^{\circ}C$		-	1.20	V
Forward valence(1)	TPMR10JH			-	1.80	V
Forward voltage <sup>(1)</sup>	TPMR10DH	I <sub>F</sub> = 10A, T <sub>J</sub> = 125°C		-	0.86	V
	TPMR10GH			-	1.00	V
	TPMR10JH			-	-	V
	TPMR10DH	T <sub>J</sub> = 25°C	I <sub>R</sub>	-	5	μΑ
	TPMR10GH TPMR10JH			-	10	μА
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	TPMR10DH			-	250	μΑ
	TPMR10GH TPMR10JH	T <sub>J</sub> = 125°C		-	500	μΑ
Junction capacitance	$1MHz, V_R = 4.0V$	CJ	140	-	pF	
	TPMR10DH TPMR10GH	IF = 0.5A, IR = 1.0A Irr = 0.25A	t <sub>rr</sub>	-	35	ns
Deviage generalizations	TPMR10JH			-	40	ns
Reverse recovery time	TPMR10DH TPMR10GH	$I_F = 1A,$ di/dt = -50A/µs,	t <sub>rr</sub>	-	60	ns
	TPMR10JH	V <sub>R</sub> = 30V		-	-	ns

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING			
TPMR10xH	TO-277A (SMPC)	6,000 / Tape & Reel			

1. "x" defines voltage from 200V(TPMR10DH) to 600V(TPMR10JH)



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

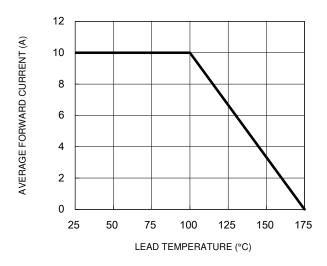


Fig.3 Typical Reverse Characteristics

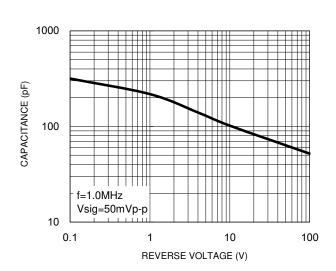
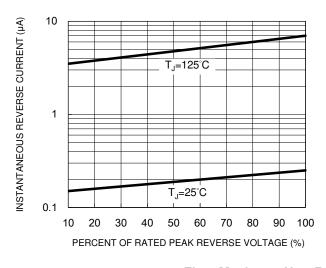


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



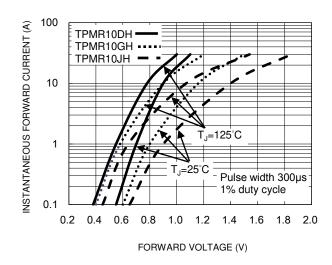
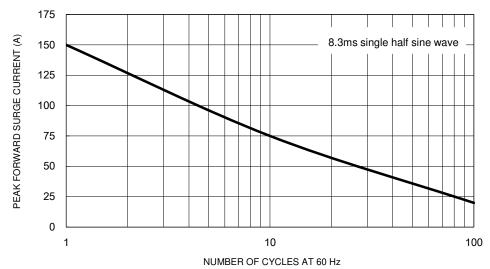


Fig.5 Maximum Non-Repetitive Forward Surge Current



3

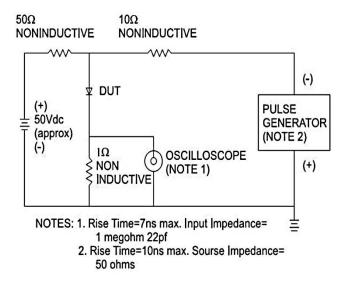


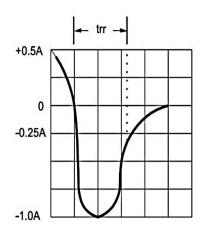
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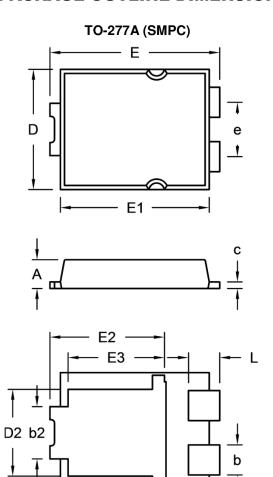
Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram





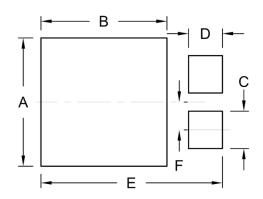


## **PACKAGE OUTLINE DIMENSIONS**



DIM.	Unit	(mm)	Unit (inch)	
DIIVI.	Min.	Max.	Min.	Max.
Α	1.000	1.200	0.039	0.047
b	1.000	1.300	0.039	0.051
b2	1.850	2.150	0.073	0.085
С	0.175	0.325	0.007	0.013
D	4.550	4.650	0.179	0.183
D2	3.170	3.470	0.125	0.137
E	6.350	6.650	0.250	0.262
E1	5.650	5.750	0.222	0.226
E2	4.235	4.535	0.167	0.179
E3	3.540	3.840	0.139	0.151
е	1.930	2.230	0.076	0.088
L	1.043	1.343	0.041	0.053

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	4.80	0.189
В	4.72	0.186
С	1.40	0.055
D	1.27	0.050
E	6.80	0.268
F	1.04	0.041

## **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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